

Docket No.: 4425-336

PATENT



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of

Hsin-Chang WU

U.S. Patent Application No. 10/722,394

Filed: November 28, 2003

For: **METHOD AND STRUCTURE FOR THE ADHESION BETWEEN DIELECTRIC LAYERS**

: : **EXPEDITED PROCEDURE**
: : **Response under 37 CFR 1.116**
: Confirmation No. 7178
:
: Group Art Unit: 2823
:
: Examiner: TRUNG Q. DANG

AMENDMENT UNDER RULE 116

BOX AF

Commissioner for Patents

PO Box 1450

Alexandria, VA 22313-1450

O.K. TO ENTER
Trung Q. Dang

Sir:

In response to the Office Action of March 7, 2005, in connection with the above-identified application, please amend the above-identified application as follows:

Amendments to the Claims: are reflected in the listing of claims, which begins on page 2 of this paper.

Remarks/Arguments: begin on page 6 of this paper.